

TIMOTHY E. MURPHY

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ACADEMIC POSITIONS

University of Idaho College of Law, Boise/Moscow, Idaho

Visiting Associate Professor of Law; Director, Entrepreneurship Law Clinic; Director, Idaho Patent Pro Bono Program; 2018-2020

Courses:

Entrepreneurship Law Clinic
Patents
Patent Drafting
Lawyering Process: Transactions

Service:

Curriculum Committee (non-voting participant)
Diversity Committee (non-voting participant)
Faculty Advisor for JD/MBA program (with Boise State University)
Faculty Advisor for Idaho Veteran Law Association (student group)
Faculty Advisor for Intellectual Property Law Society (student group)
Panel Moderator, University of Idaho Critical Legal Studies Journal Symposium:
Technology in the Law: is it leveling the playing field?, March 29, 2019

Concordia University School of Law, Boise, Idaho

Adjunct Professor, 2015-2018

Courses:

Internet Law
Intellectual Property

Boise State University, Boise, Idaho

Adjunct Professor, 2010

Courses:

Patent Fundamentals for Engineers

EDUCATION

University of Michigan Law School, Ann Arbor, Michigan

Juris Doctor, May 2008

University of Michigan, Ann Arbor, Michigan

Master of Science in Electrical Engineering, May 2004

Specialized in Solid State Electronics and Advanced Materials

Boise State University, Boise, Idaho

Bachelor of Science in Electrical Engineering, May 2002

Magna Cum Laude

Founding president of local Eta Kappa Nu chapter

SELECTED PROFESSIONAL EXPERIENCE

Micron Technology, Inc., Boise, Idaho (2010-2018)

Sr. Patent and Trademark Counsel; Technology Licensing Counsel

Primary Practice Areas: patent and trademark portfolio management; patent litigation; intellectual property licensing; M&A contract drafting and diligence; commercial contracts; trade secret program management

Zarian, Midgley, & Johnson, PLLC, Boise, Idaho (2010)

Associate Attorney

Primary Practice Areas: patent prosecution; commercial and IP litigation

Marger Johnson & McCollom, P.C., Portland, Oregon (2006-2009)

Associate Attorney; Patent Agent

Primary Practice Areas: Patent and trademark prosecution; commercial and IP litigation

Micron Technology, Inc., Boise, Idaho (1995-2002)

DRAM R&D Engineer; Manufacturing Engineer; Manufacturing Technician

U.S. Navy, Norfolk, Virginia (1988-1994)

Machinist's Mate (Nuclear)

Received honorable discharge and several commendations including the Southwest Asia Service Medal for participation in Operation Desert Storm

PRO BONO EXPERIENCE

- Guardian *ad litem* representations in child protection cases (2014-present)
- Hague Convention child abduction case (2016-2017)
- Divorce/custody cases (2009-2016)
- Small business dispute for refugee family (2014)
- § 1983 prisoner civil rights claim (2009-2010)

BAR ADMISSIONS

- Idaho State and Federal Courts
- U.S. Patent and Trademark Office (Reg. No. 59,092)
- California State and Federal Courts (Inactive)
- Oregon State and Federal Courts (Inactive)

LOCAL COMMUNITY ENGAGEMENT

- Idaho Volunteer Lawyers Program, Policy Council member (2010-present)
- Idaho Technology Council Tech2Market Committee, member (2018-present)
- Idaho Military Legal Alliance, member (2018-present)
- Kuna Entrepreneur's Bootcamp, February 2019 (supervised students presenting to local entrepreneurs on business and intellectual property topics)

- Intellectual Property Section of the Idaho State Bar, past Vice-Chair and Secretary (2010-Present)
- Business and Corporate Law Section of the Idaho State Bar, member (2018-Present)
- Child Protection Section of the Idaho State Bar, member (2018-Present)
- Micron Legal Department Community Service Committee, Chairperson (2014-2018)

NATIONAL AND REGIONAL ENGAGEMENT

- AALS Clinical Section, Membership, Outreach, and Training Committee, member (2019-present)
- AALS Conference on Clinical Legal Education, working group facilitator (May 2019)
- Northwest Clinical Law Conference, Planning Committee member (May-Nov. 2019)

LAW-RELATED WORKS IN PROGRESS & PUBLICATIONS

- Work-in-Progress: *An Instance of Open Hardware: A Different Approach to Free and Open Source Hardware Licensing*, submitting for publication in Fall 2019 cycle.
 - Presented at AALS Conference on Clinical Legal Education Works In Progress Session (May 7, 2019)
- Timothy E. Murphy, *University of Idaho's Entrepreneurship Law Clinic: Providing Free Legal Services for Idaho Ventures*, *The Advocate*, Vol. 62, No. 3/4, at p. 34.

AWARDS

- Denise O-Donnell-Day Pro Bono Award (2011)

PEER-REVIEWED TECHNICAL JOURNAL PUBLICATIONS

- T.E. Murphy, D.Y. Chen, E. Cagin, and J.D. Phillips, *Electronic Properties Of ZnO Epilayers Grown On C-Plane Sapphire By Plasma-Assisted Molecular Beam Epitaxy*, Proceedings from the 22nd North American Molecular Beam Epitaxy Conference, October 10-13, 2004, Banff, Canada, *Journal of Vacuum Science and Technology B*, Volume 23 (3), 1277-1280 (2005).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, *Growth And Electronic Properties Of ZnO Epilayers By Plasma-Assisted Molecular Beam Epitaxy*, Proceedings from the 2004 U.S. Workshop on the Physics and Chemistry of II-VI Materials, October 5-7, 2004, Chicago, Illinois, *Journal of Electronic Materials*, Volume 34 (6), 699-703 (2005).
- T. E. Murphy, J. O. Blaszcak, K. Moazzami, W. E. Bowen, And J. D. Phillips, *Properties Of Electrical Contacts On Bulk And Epitaxial n-Type ZnO*, Proceedings from the 46th TMS Electronic Materials Conference, June 23-25, 2004, Notre Dame, Indiana, *Journal of Electronic Materials*, Volume 34 (4), 389-394 (2005).
- T.E. Murphy, S. Walavalkar, and J.D. Phillips, *Epitaxial growth and surface modeling of ZnO on c-plane Al₂O₃*, *Applied Physics Letters*, Volume 85 (26), 6338-6340 (2004).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, *Electronic Properties Of Ferroelectric BaTiO₃/MgO Capacitors On GaAs*, *Applied Physics Letters*, Volume 85 (15), 3208-3210 (2004).

- D. Chen, T. E. Murphy, S. Chakrabarti, and J. D. Phillips, *Optical Waveguiding In BaTiO₃/MgO/Al_xO_y/GaAs Heterostructures*, Applied Physics Letters, Volume 85 (22), 5206-5208 (2004).
- D.Y. Chen, T.E. Murphy, and J.D. Phillips, *Deposition Of BaTiO₃ Thin Films And MgO Buffer Layers On Patterned GaAs Substrates for Integrated Optics Applications*, Materials Research Society 2003 Fall Meeting Proceedings, Volume 784, C11.23 (2004).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, *Integration of BaTiO₃ Ferroelectric Thin Films with GaAs for Functional Devices*, Proceedings of the 15th Biennial University/Government/Industry Microelectronics Symposium, June 30-July 2, 2003, Boise, Idaho (2003).

ISSUED PATENTS

- US Patent Number 7,732,882, *Method and system for electrically coupling a chip to chip package*, issued June 8, 2010.
- US Patent Number 7,489,875, *System and method for multiple bit optical data transmission in memory systems*, issued February 10, 2009.
- US Patent Number 7,355,273, *Semiconductor dice having back side redistribution layer accessed using through-silicon vias, methods*, issued April 8, 2008.
- US Patent Number 7,335,985, *Method and system for electrically coupling a chip to chip package*, issued February 26, 2008.
- US Patent Number 7,254,331, *System and method for multiple bit optical data transmission in memory systems*, issued August 7, 2007.
- US Patent Number 7,015,559, *Method and system for electrically coupling a chip to chip package*, issued March 21, 2006.
- US Patent Number 6,936,489, *Method and system for electrically coupling a chip to chip package*, issued August 30, 2005.
- US Patent Number 6,914,317, *Thin microelectronic substrates and methods of manufacture*, issued July 5, 2005.
- US Patent Number 6,831,301, *Method and system for electrically coupling a chip to chip package*, issued December 14, 2004.
- US Patent Number 6,800,930, *Semiconductor dice having back side redistribution layer accessed using through-silicon vias, and assemblies*, issued October 5, 2004.
- US Patent Number 6,693,342, *Thin microelectronic substrates and methods of manufacture*, divisional from 6,303,469, issued February 17, 2004.
- US Patent Number 6,303,469, *Thin microelectronic substrates and methods of manufacture*, issued October 16, 2001.

TECHNICAL CONFERENCE PRESENTATIONS

- 2005 American Society for Engineering Education Annual Conference and Exhibition, June 12-15, 2005, Portland, Oregon.
- 22nd North American Molecular Beam Epitaxy Conference, October 10-13, 2004, Banff, Alberta, Canada.
- The 2004 U.S. Workshop on the Physics and Chemistry of II-VI Materials, October 5-7, 2004, Chicago, Illinois.
- The 2004 TMS Electronic Materials Conference and Exhibition, June 23-25, 2004, South Bend, Indiana.

- 15th Biennial University/Government/Industry Microelectronics Symposium, June 30-July 2, 2003, Boise, Idaho. Oral Presentation.
- The 2003 TMS Electronic Materials Conference, June 25-27, 2003, Salt Lake City, Utah.